MSKSEMI 美森科







TVC



TSS



MOV



GDT



DIE

MS30N06DF

Product specification





Features

- 60V,30A, RDS(ON)=28mΩ@VGS=10V
- Improved dv/dt capability
- Fast switching
- Green Device Available

Application

- Motor Drive
- Power Tools
- LED Lighting

| BVDSS | RDSON | ID |
|-------|-------|-----|
| 60V | 28mΩ | 30A |

Reference News

| PACKAGE OUTLINE | Pin Configuration | Marking |
|-----------------|-------------------|-------------------|
| DFN3X3-8L | G | 30N06DF MS *** |

Absolute Maximum Ratings Tc=25°C unless otherwise noted

| Symbol | Parameter | Rating | Units |
|--------|---------------------------------------|------------|-------|
| Vps | Drain-Source Voltage | 60 | V |
| Vgs | Gate-Source Voltage | ±20 | V |
| - | Drain Current - Continuous (Tc=25°C) | 30 | Α |
| ID . | Drain Current - Continuous (Tc=100°C) | 15 | Α |
| Ірм | Drain Current - Pulsed ¹ | 74 | Α |
| Po | Power Dissipation (Tc=25°C) | 31 | W |
| | Power Dissipation - Derate above 25°C | 0.32 | W/°C |
| Тѕтс | Storage Temperature Range | -55 to 150 | °C |
| TJ | Operating Junction Temperature Range | -55 to 150 | °C |

Thermal Characteristics

| Symbol | Parameter | Тур. | Max. | Unit |
|--------|--|------|------|------|
| Reja | Thermal Resistance Junction to ambient | | 62 | °C/W |
| Reuc | Thermal Resistance Junction to Case | | 3.1 | °C/W |



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Off Characteristics

| Symbol | Parameter | Conditions | Min. | Тур. | Max. | Unit |
|------------|---|--|------|------|------|------|
| BVDSS | Drain-Source Breakdown Voltage | Vgs=0V , Ip=250uA | 60 | | | V |
| △BVoss/△TJ | BV _{DSS} Temperature Coefficient | Reference to 25°C , I _D =1mA | | 0.06 | | V/°C |
| Ipss | Drain-Source Leakage Current | V _{DS} =60V , V _{GS} =0V , T _J =25°C | | | 1 | uA |
| IDSS | _ | V _{DS} =48V , V _{GS} =0V , T _J =125°C | | | 10 | uA |
| Igss | Gate-Source Leakage Current | Vgs= ±20V , Vps=0V | | | ±100 | nA |

On Characteristics

| Rds(on) | Static Drain-Source On-Resistance | Vgs=10V , Ip=10A | | 28 | 36 | mΩ |
|----------------------|---|---|--|------|-----|-------|
| T CDS(ON) | State Brain Goding on Neolistanes | Vgs=4.5V , ID=5A | | 36 | 45 | mΩ |
| V _{GS} (th) | Gate Threshold Voltage | Vgs=Vds , ld =250uA | | 1.6 | 2.5 | V |
| △VGS(th) | V _{GS(th)} Temperature Coefficient | | | -4.6 | | mV/°C |
| gfs | Forward Transconductance | V _{DS} =10V , I _D =8A | | 11 | | S |

Dynamic and switching Characteristics

| Qg | Total Gate Charge ^{3,4} | | | 16.4 | 1 | |
|---------------------|------------------------------------|---|---|------|---|-----|
| Qgs | Gate-Source Charge ^{3, 4} | Charge ^{3 , 4} V _{DS} =30V , V _{GS} =10V , I _D =10A | | 3.1 | - | nC |
| Qgd | Gate-Drain Charge ^{3,4} | | | 3.7 | | |
| T _{d(on)} | Turn-On Delay Time ^{3,4} | | | 4.6 | - | |
| Tr | Rise Time ^{3 , 4} | V_{DD} =30 V , V_{GS} =10 V , R_{G} =6 Ω | | 14.8 | | ns |
| T _{d(off)} | Turn-Off Delay Time ^{3,4} | lo=1A | | 27.2 | - | 113 |
| Tf | Fall Time ^{3, 4} | | - | 7.8 | - | |
| Ciss | Input Capacitance | | | 1180 | - | |
| Coss | Output Capacitance | V _{DS} =30V , V _{GS} =0V , F=1MHz | | 80 | - | pF |
| Crss | Reverse Transfer Capacitance | | | 52 | | |

Drain-Source Diode Characteristics and Maximum Ratings

| Symbol | Parameter | Conditions | Min. | Тур. | Max. | Unit |
|--------|---------------------------|---|------|------|------|------|
| ls | Continuous Source Current | V _G =V _D =0V, Force Current | | | 30 | Α |
| lsм | Pulsed Source Current | , roros sanone | | | 60 | Α |
| Vsp | Diode Forward Voltage | Vgs=0V , Is=1A , TJ=25°C | | | 1.2 | V |

Note:

- 1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
- 2. $V_{DD}=50V, V_{GS}=10V, L=0.1 \text{mH}, I_{AS}=23 \text{A.}, R_{G}=25 \Omega, Starting T}_{J}=25 ^{\circ}\text{C}$
- 3. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.
- 4. Essentially independent of operating temperature.

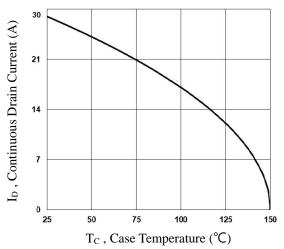


Fig.1 Continuous Drain Current vs. T_c

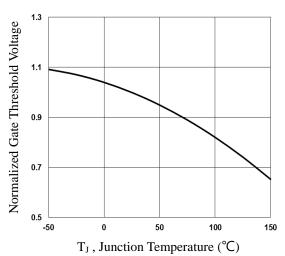


Fig.3 Normalized V_{th} vs. T_J

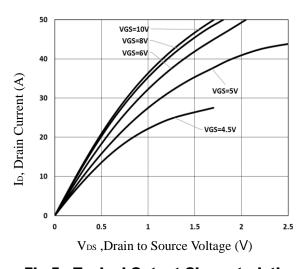


Fig.5 Typical Output Characteristics

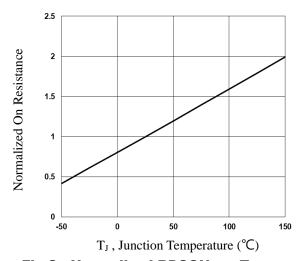


Fig.2 Normalized RDSON vs. T_J

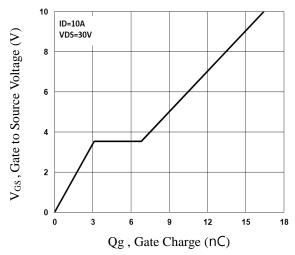


Fig.4 Gate Charge Waveform

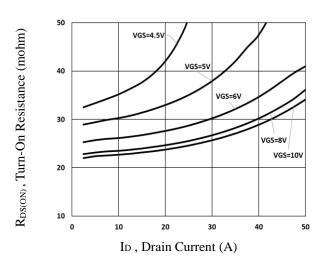


Fig.6 Turn-On Resistance vs. ID

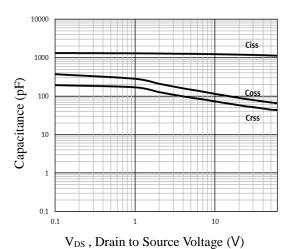


Fig.7 Capacitance Characteristics

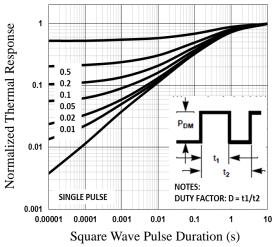


Fig.9 Normalized Transient Impedance

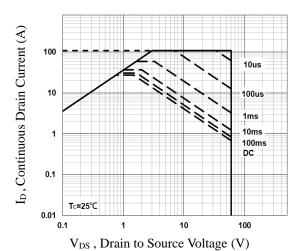
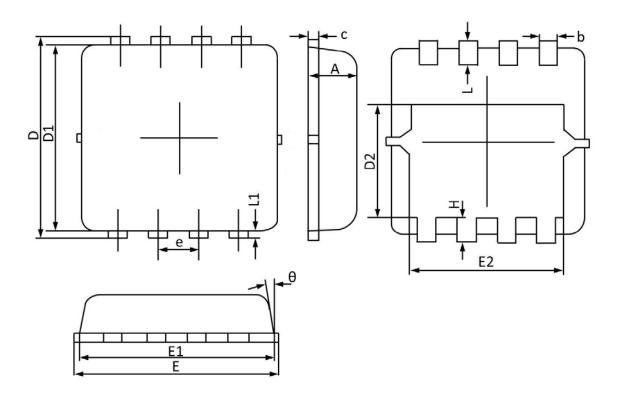


Fig.8 Maximum Safe Operation Area



PDFN3x3 PACKAGE INFORMATION



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|-----------|----------------------------------|------------|-----------------------------|-------|
| | MAX | MIN | MAX | MIN |
| A | 0.900 | 0.700 | 0.035 | 0.028 |
| b | 0.350 | 0.240 | 0.014 | 0.009 |
| С | 0.250 | 0.100 | 0.010 | 0.004 |
| D | 3.450 | 3.050 | 0.136 | 0.120 |
| D1 | 3.200 | 2.900 | 0.126 | 0.114 |
| D2 | 1.850 | 1.350 | 0.073 | 0.053 |
| E | 3.400 | 3.000 | 0.134 | 0.118 |
| E1 | 3.250 | 2.900 | 0.128 | 0.114 |
| E2 | 2.600 | 2.350 | 0.102 | 0.093 |
| e | 0.65BSC | | 0.026BSC | |
| Н | 0.500 | 0.300 | 0.020 | 0.012 |
| L | 0.500 | 0.300 | 0.020 | 0.012 |
| L1 | 0.200 | 0.070 | 0.008 | 0.003 |
| θ | 12° | 0 ° | 12° | 0° |

REEL SPECIFICATION

| P/N | PKG | QTY |
|-----------|-----------|------|
| MS30N06DF | DFN3X3-8L | 5000 |



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BXP4N65F AOL1454G WMJ80N60C4 BXP2N20L BXP2N65D BXT1150N10J BXT1700P06M TSM60NB380CP ROG RQ7L055BGTCR
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